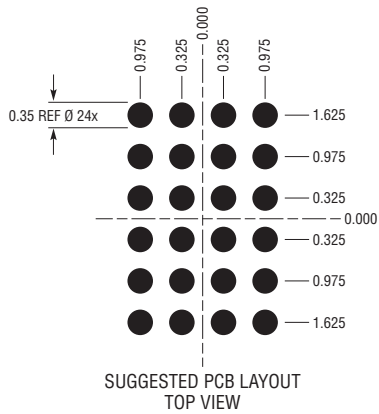
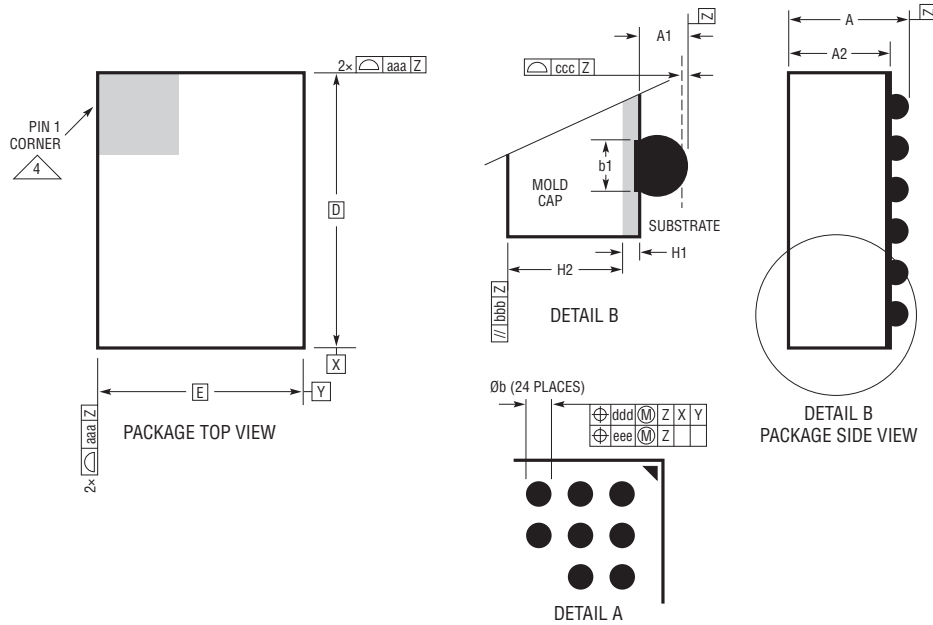
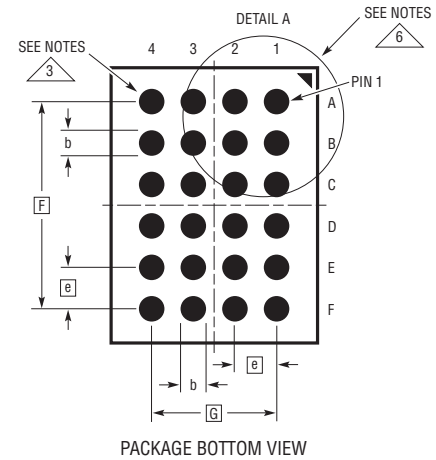


**BGA Package**  
**24-Lead (4mm × 3mm × 1.48mm)**  
 (Reference LTC DWG# 05-08-1658 Rev A)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.32	1.48	1.64	
A1	0.23	0.30	0.37	BALL HT
A2	1.09	1.18	1.27	
b	0.35	0.40	0.45	BALL DIMENSION
b1	0.32	0.35	0.38	PAD DIMENSION
D		4.00		
E		3.00		
e		0.65		
F		3.25		
G		1.95		
H1		0.18 REF		SUBSTRATE THK
H2		1.00 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.10	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 24



NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6  PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG  $\mu$ Module PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

